HDI Stackup Planner — Detailed Report for HSP-189472 Option A

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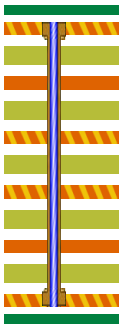
Customer Input

Part Number/ Rev : **amINO/ 1.0**
PCB Size in X : 0.51 inches X 0.59 inches
Number of layers : 6 **PCB Thickness** :0.031 inches
Material : NP175 **Outer Layer** :Signal

MicroVias depicted by



		Finished Copper Weight	Finished Thickness (inches)
	SOLDER MASK		0.0005
L-1	TOP SIGNAL	1 Oz	0.0014
	DIELECTRIC		0.0035
L-2	PLANE	0.5 Oz	0.0007
	DIELECTRIC		0.0040
L-3	SIGNAL	0.5 Oz	0.0007
	DIELECTRIC		0.0085
L-4	SIGNAL	0.5 Oz	0.0007
	DIELECTRIC		0.0040
L-5	PLANE	0.5 Oz	0.0007
	DIELECTRIC		0.0035
L-6	BOTTOM SIGNAL	1 Oz	0.0014
	SOLDER MASK		0.0005
	Total Thickness	**0.0301 (inches)**	

Customer Saved Impedance Results

Layer	Impedance Model	Impedance (ohms)	Trace Width (mils)	Space (mils)
Layer 1	Soldermask Coated Microstrip Single-ended	51.7	5	--
Layer 1	Soldermask Coated Microstrip Differential Pair	90.03	5	6
Layer 3	Stripline Single-ended	51.11	4.5	--

Stackup Details

Number of Layers	Number of Signal Layers	Number of Sequential Laminations	Number of Plane Layers	Maximum Number of Laser Drills	Mechanical Drills
6	4	0	2	0	1

Technology Parameters and Cost Index

PCB TECHNOLOGY LEVELS	Level 1	Level 2	Level 3	Level 4
Mechanical Micro via Drill diameter (in mils)	8.00	8.00	7.00	6.00
Mechanical Micro via Pad diameter (in mils)	16.00	14.00	13.00	12.00
Micro Via Drill Diameter (in mils)	6.00	6.00	6.00	4.00
Micro Via Pad Diameter (in mils)	14.00	12.00	12.00	10.00
Trace Width Top Layer (in mils)	5.00	4.50	4.00	4.00
Trace width Inner Buildup Layers (in mils)	4.50	4.00	3.50	3.00
Trace Width Inner Core Layers (in mils)	4.50	4.00	3.50	3.00
Trace Width Bottom Layer (in mils)	5.00	4.50	4.00	4.00
Cost Index	1.9	2.2	2.7	3.2

Via Set Information

This stack up supports the following via set
L1-L6